

Epoxy Curing Agent GHF2250

I Description

GHF2250 is a kind of phenolic resin which can cure fast under low temperature. It is developed by reaction of BPA and epoxy resin. Pure epoxy powder coatings made of GHF2250 is characteristic of good properties of flow, anti-corrosive and mechanism. GHF2250 can react with normal epoxy resin and can cure under low temperature with great performance.

II Technical data

Property	Test Method	Value
Appearance	Visualization	Transparent granule or powder
Softening point	GB/T 4507-1999	80~90℃
Phenolic hydroxyl equivalent	Company Standard	230~250 (g/eq)
Solid Content	GB/T 1725-2008	≥99%

III Application

- 1 Reaction ratio of GHF2250 against E-12(EEW: 800~850) is from 1:4 to 1:6. The dosage of GHF2250 varies according to the EEW of epoxy resin.
- 2 GHF2250 contains no catalyst. Extra catalysts can be added to adjust the reaction speed when necessary.
- 3 Due to the reaction of GHF2250 is very fast, the extruding temperature shall be well controlled and no higher than 100℃. The RM supply during the producing shall be consistent to avoid possible RM gelatinization.

IV Recommended Formula (150℃/20minute)

S.N.	RM	Supplier	Formula I	Formula II	Formula III	Formula IV
1	E-12	SSC	228.2	240	-	-
2	E-14	HengYuan	-	-	222	234
3	GH2250	SSC	51.8	40	58.0	46.0
4	GLP588	SSC	5	5	5	5
5	2-MI		1.5	1.5	1.5	1.5
6	BLC701B	SSC	4	4	4	4
7	Benzoin	SSC	2	2	2	2
8	R-760(TiO ₂)	SSC	120	120	120	120
9	BaSO ₄ ↓	DongFeng	87.5	87.5	87.5	87.5
Total			500	500	500	500
Film thickness: μm			60~80	60~80	60~80	60~80
Impact(direct/reverse): kg.cm			50	50	50	50

V Package, Storage & Handling

Available in polyethylene-lined, multi-ply paper bags, N.W. 25KGS/Bag.

Store in closed containers; avoid contact with skin and eyes; wear dust mask when operating.

